GENERAL PROPERTIES

	PROPERTY	TYPICAL VALUE	DIRECTION	CONDITION	TEST METHOD
Thermal	Glass Transition Temperature, Tg	185	°C	A	DMA IPC-TM-650 2.4.24.2
		180	°C	A	DSC IPC-TM650 2.4.25
	Thermal Expansion, Z CTE	40	ppm/°C	A	Before Tg, IPC-TM-650 2.4
		210	ppm/°C	A	After Tg, IPC-TM-650 2.4
	Decomposition Temperature, Td	355	°C	A	TMA IPC-TM650 2.4.24.6
	Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T288	30	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T300	15	minutes	A	TMA IPC-TM650 2.4.24
Electrical	Dielectric Constant (Dk)	4.90	-	1 MHz	IPC-TM-650 2.5.5.9
	Dissipation Factor (Df)	0.0180	-	1 MHz	IPC-TM-650 2.5.5.9
	Volume Resistivity	2.20E+08	MΩ·cm	After moisture resistance	IPC-TM-650 2.5.17.1
	Surface Resistivity	7.90E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
	Dielectric Breakdown	45+NB	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Physical	Thermal Conductivity	0.62	W/m·K	100°C	ASTM D5470
	Water Absorption	0.08	%	D-24/23	IPC-TM-650 2.6.2.1
	Copper Peel Strength	1.40(8.0)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
	Flammability	94V-0	-	A	UL

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[1] Typical values are a representation of an average value for the population of the property. For specification values contact SYTECH Corporation. The information in this data sheet is intended to assist you in designing with SYTECH's circuit materials. It is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose or that any results shown in this data sheet will be achieved by a user for a particular purpose. The user is responsible for determining the suitability of SYTECH's circuit materials for each application.